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United States Patent [19]**Tajima et al.**[11] **Patent Number:** **5,726,491**[45] **Date of Patent:** **Mar. 10, 1998**[54] **TAPE CARRIER PACKAGE**

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[58] **Field of Search** 257/666, 668,
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[57] **ABSTRACT**

A tape carrier package of the invention includes: an insulating film having a device hole; a conductor pattern formed on the insulating film; and conductor leads electrically connected to the conductor pattern and projected inward beyond the edge of the device hole, and the conductor leads is electrically connected to electrode pads of a semiconductor chip. In this arrangement, the electrode pads of the semiconductor chip are arranged in at least two rows which are parallel to opposite two sides of the semiconductor chip, the two opposite rows of pads are disposed closer to the center of the two rows than to the edge of semiconductor chip, and the element-forming surface of the entire semiconductor chip containing the region between the insulating film and the semiconductor chip, is sealed with a sealing resin, except the part of the electrode pads.

7 Claims, 14 Drawing Sheets

